

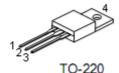
1. Features

- n $R_{DS(on)}$ =10.5m Ω @ V_{GS} =10V
- n Lead free and green device available
- n Low Rds-on to minimize conductive loss
- n High avalanche current

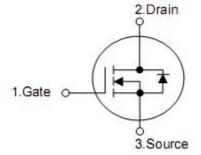
2. Applications

- n Power supply
- n UPS
- n Battery management system

3.Symbol







Pin	Function			
1	Gate			
2	Drain			
3	Source			
4	Drain			



4. Absolute maximum ratings

(T_A=25°C,unless otherwise noted)

Parameter		Symbol	Rating	Units
Drain-source voltage		V _{DSS}	60	V
Gate-source voltage		V _{GSS}	<u>+</u> 25	V
Continuous drain current	T _C =25°C	. I _D 3	50	А
	T _C =100°C		35	Α
Pulse drain current	T _C =25°C	I _{DP} ⁴	250	Α
Avalanche current		I _{AS} ⁵	15	А
Avalanche energy,		E _{AS} ⁵	120	mJ
Maximum power dissipation	T _C =25 °C	P _D	88	W
	T _C =100°C	гD	44	W
Junction & storage temperature range		T _J ,T _{STG}	-55-175	$^{\circ}$

5. Thermal characteristics

Parameter	Symbol	Rating		Unit	
		To-252	To-220	Offic	
Thermal resistance, Junction-ambient	$R_{\theta JA}$	100	62.5	°C/W	
Thermal resistance, Junction-case	$R_{ heta JC}$	1.1	1.7	°C/W	



6. Electrical characteristics

(T_A=25°C,unless otherwise noted)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Units
Drain-source breakdown voltage	BV _{DSS}	V _{GS} =0V,I _{DS} =250μA	60		-	V
Diam-source breakdown voltage	D V DSS	•				V
Zero gate voltage drain current	I _{DSS}	V _{DS} =48V, V _{GS} =0V	-	-	1	μΑ
		T _J =125°C	-	-	20	
Gate threshold voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}$, $I_{D}=250\mu A$	2.0	3.0	4.0	V
Gate leakage current	I _{GSS}	V _{GS} = <u>+</u> 25V, V _{DS} =0V	-	-	<u>+</u> 100	nA
Drain-source on-resistance	R _{DS(on)} ¹	V _{GS} =10V,I _D =30A	-	10.5	12.5	mΩ
Gate resistance	R_g	V _{DS} =0V, V _{GS} =0V,f=1MHz	-	1.0	-	Ω
Diode forward voltage	V _{SD} ¹	I _{SD} =30A, V _{GS} =0V	-	8.0	1.3	V
Diode continuous forward current	ls ³		-	-	50	Α
Reverse recovery time	t _{rr}	I _F =30A ,	-	32	-	nS
Reverse recovery charge	Q _{rr}	dl _{SD} /dt=100A/µs	-	60	-	nC
Input capacitance	C _{iss}	V _{DS} =25V,V _{GS} =0V, f=1MHz	-	2060	-	
Output capacitance	Coss		-	755	-	pF
Reverse transfer capacitance	C _{rss}	1-11/11/2	-	375	-	
Turn-on delay time	t _{d(on)}		-	14	-	
Rise time	t _r	V_{DD} =30V, I_{D} =30A, R_{G} =5 Ω , V_{GS} =10V	-	13	-	nS
Turn-off delay time	$t_{d(off)}$		-	20	-	
Fall time	t _f		-	7.5	-	
Total gate charge	Qg	V _{DS} =48V, V _{GS} =10V	-	50	-	
Gate-source charge	Q _{gs}	I _{DS} =30A	-	12		nC
Gate-drain charge	Q _{gd}		-	17		
		1			1	

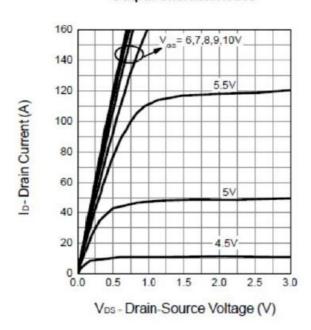
Note:1: Pulse test; pulse width≤300us duty cycle≤2%.

- 2: Guaranteed by design, not subject to production testing.
- 3: Package limitation current is 50A.Calculated continuous current based on maximum allowable junction temperature.
- 4: Repetitive rating, pulse width limited by max junction temperature.
- 5: Starting $T_J=25^{\circ}C$, L=0.5mH, $I_{AS}=31A$.

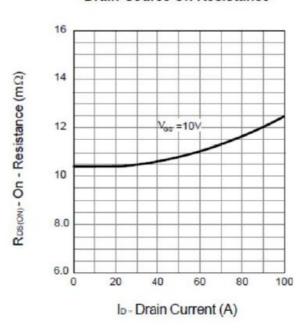


7. Test circuits and waveforms

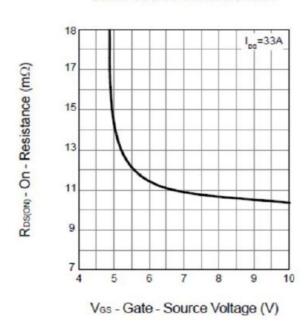
Output Characteristics



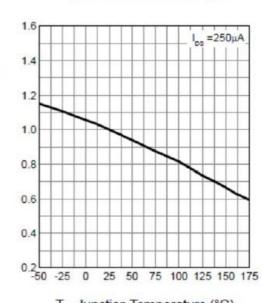
Drain-Source On Resistance



Drain-Source On Resistance



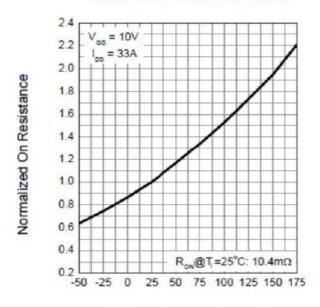
Gate Threshold Voltage



Normalized Threshold Vlotage

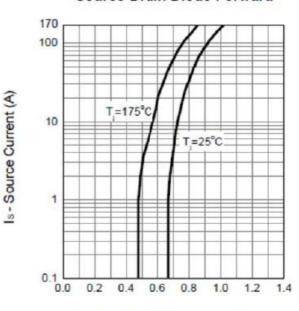


Drain-Source On Resistance



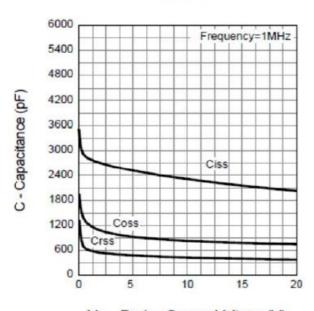
T_j- Junction Temperature (°C)

Source-Drain Diode Forward



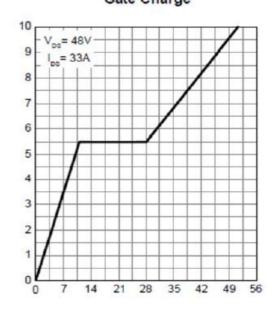
Vsb - Source-Drain Voltage (V)

Capacitance



Vps - Drain - Source Voltage (V)

Gate Charge



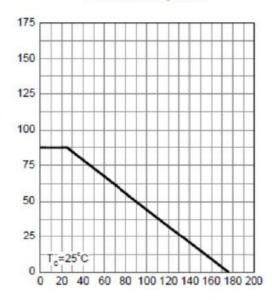
Qs - Gate Charge (nC)

Vos - Gate-source Voltage (V)



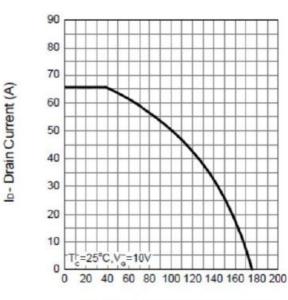
Pbt- Power (W)

Power Dissipation



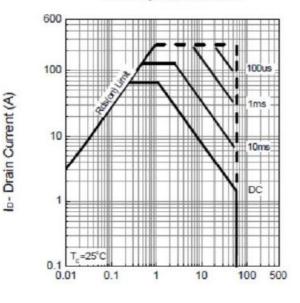
T_i- Junction Temperature (°C)

Drain Current



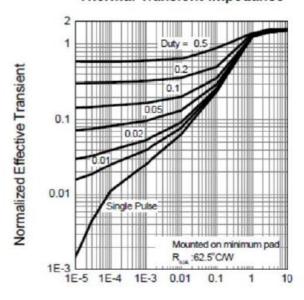
T_j - Junction Temperature (°C)

Safe Operation Area



Vps - Drain - Source Voltage (V)

Thermal Transient Impedance



Square Wave Pulse Duration (sec)